



(12) **Patent Application Publication**
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(43) **Pub. Date:** **Jun. 27, 2024**

It would be helpful to provide a wafer separation apparatus and method, and a method for manufacturing a silicon wafer in which poor wafer separation can be easily prevented. A wafer separation apparatus **1** includes an injection port **2** configured to inject a fluid, a rolling element **3**, and a holder **4** configured to movably hold the rolling element **3** in a rollable and integral manner, to be reciprocatable and biased to one side in a reciprocating direction, and to be integrally connected to the injection port **2**.

Dec. 23, 2022 (JP) 2022-207614

